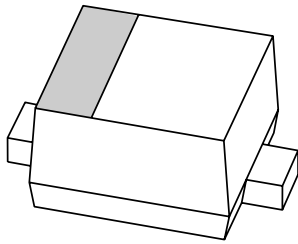


# DATA SHEET



## **BAS716** Low-leakage diode

Product specification

2003 Nov 07

# Low-leakage diode

# BAS716

## FEATURES

- Plastic SMD package
- Low leakage current: typ. 0.2 nA
- Switching time: typ. 0.6 μs
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

## APPLICATION

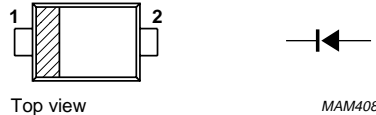
- Low leakage current applications in surface mounted circuits.

## DESCRIPTION

Epitaxial medium-speed switching diode with a low leakage current in an ultra small SOD523 (SC-79) SMD plastic package.

## PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Top view MAM408

**Marking code:** S1.  
The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD523; SC-79) and symbol.

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAS716	–	plastic surface mounted package; 2 leads	SOD523

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage		–	85	V
V <sub>R</sub>	continuous reverse voltage		–	75	V
I <sub>F</sub>	continuous forward current	see Fig.2; note 1	–	200	mA
I <sub>FRM</sub>	repetitive peak forward current		–	500	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; T <sub>j</sub> = 25 °C prior to surge; see Fig.4 t <sub>p</sub> = 1 μs t <sub>p</sub> = 1 ms t <sub>p</sub> = 1 s	–	4 1 0.5	A A A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; note 1	–	250	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C

## Note

1. Device mounted on a FR4 printed-circuit board.

## Low-leakage diode

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**ELECTRICAL CHARACTERISTICS**

$T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_F$	forward voltage	$I_F = 1\text{ mA}$	0.77	0.9	V
		$I_F = 10\text{ mA}$	0.85	1	V
		$I_F = 50\text{ mA}$	0.92	1.1	V
		$I_F = 150\text{ mA}$	1.02	1.25	V
$I_R$	reverse current	$V_R = 75\text{ V}$	0.2	5	nA
		$V_R = 75\text{ V}; T_j = 150\text{ °C}$	3	80	nA
		$V_R = 100\text{ V}$	0.3	–	nA
$C_d$	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz};$ see Fig.6	2	–	pF
$t_{rr}$	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}; R_L = 100\ \Omega;$ measured at $I_R = 1\text{ mA}$	0.6	3	$\mu\text{s}$

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	450	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point	note 2	120	K/W

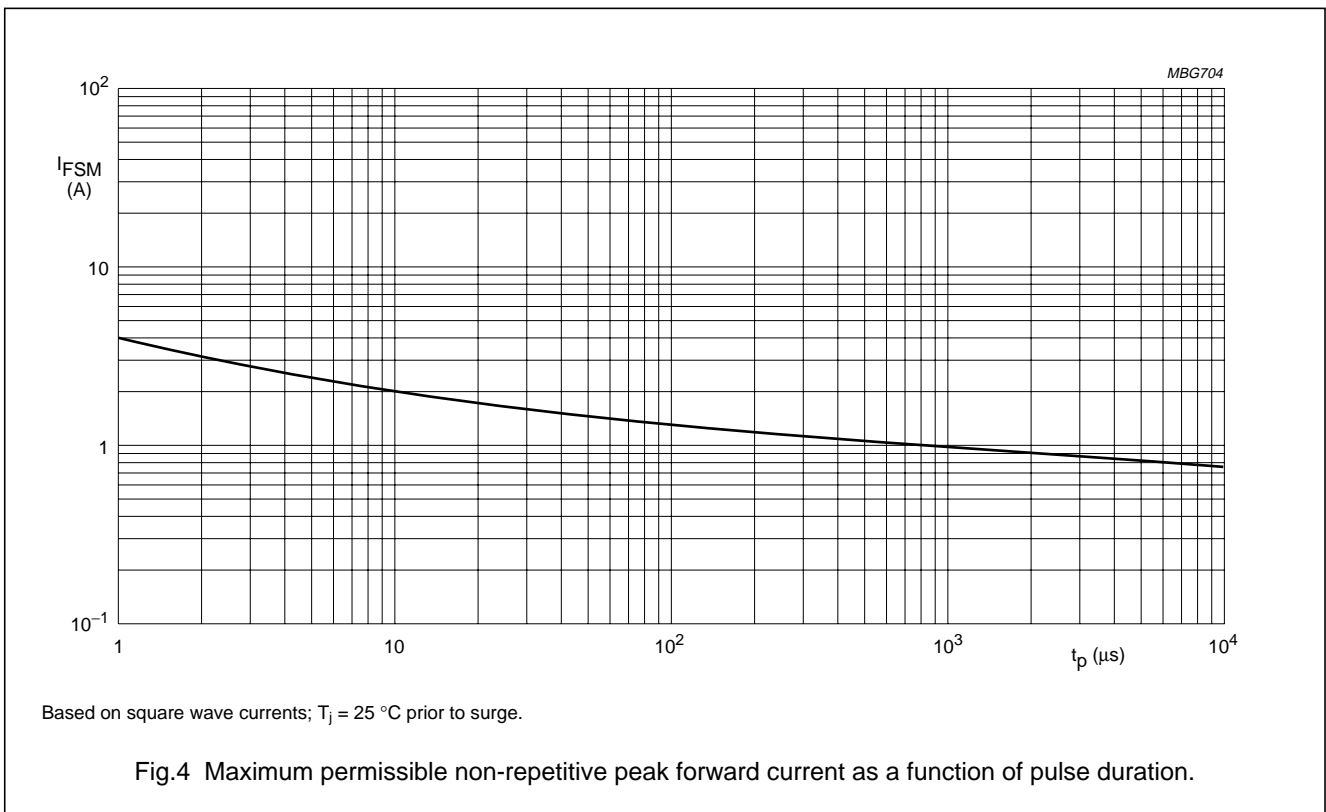
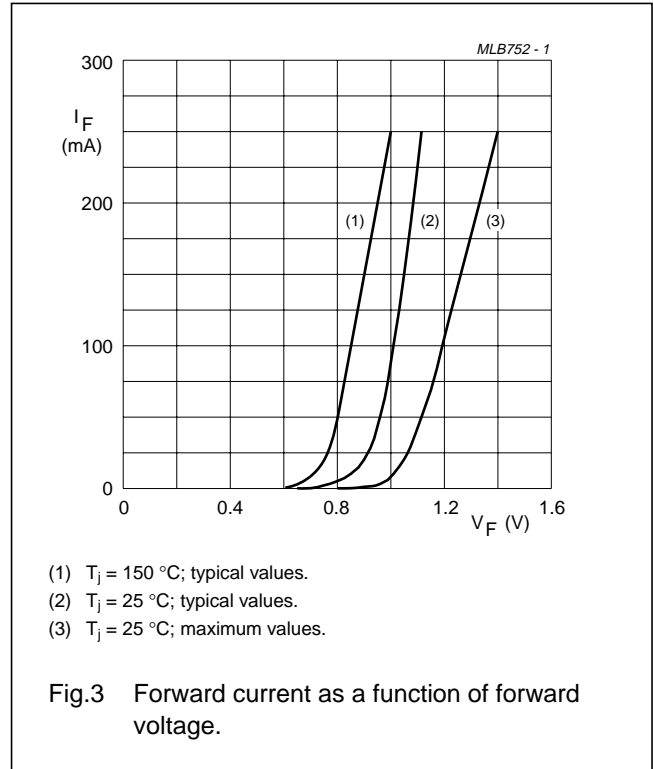
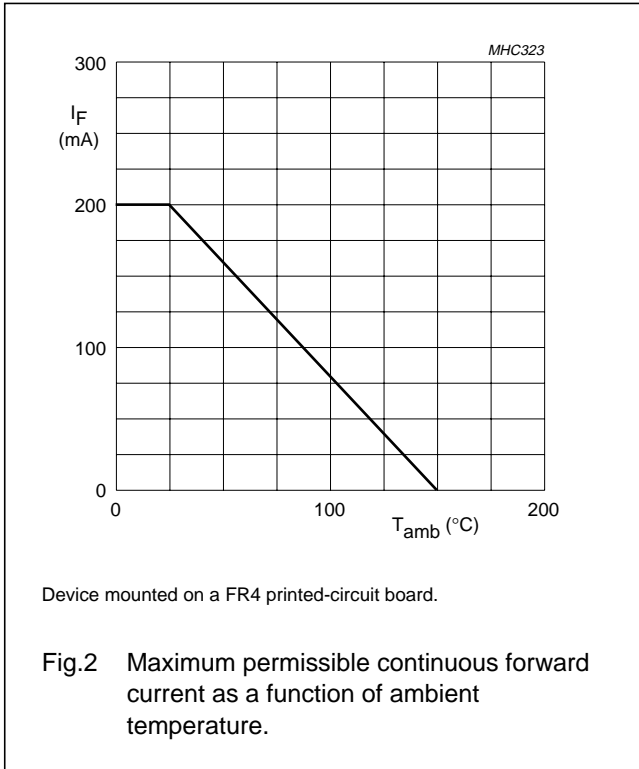
**Notes**

1. Device mounted on a FR4 printed-circuit board. Refer to SOD523 (SC-79) standard mounting conditions.
2. Soldering point of the cathode tab.

Low-leakage diode

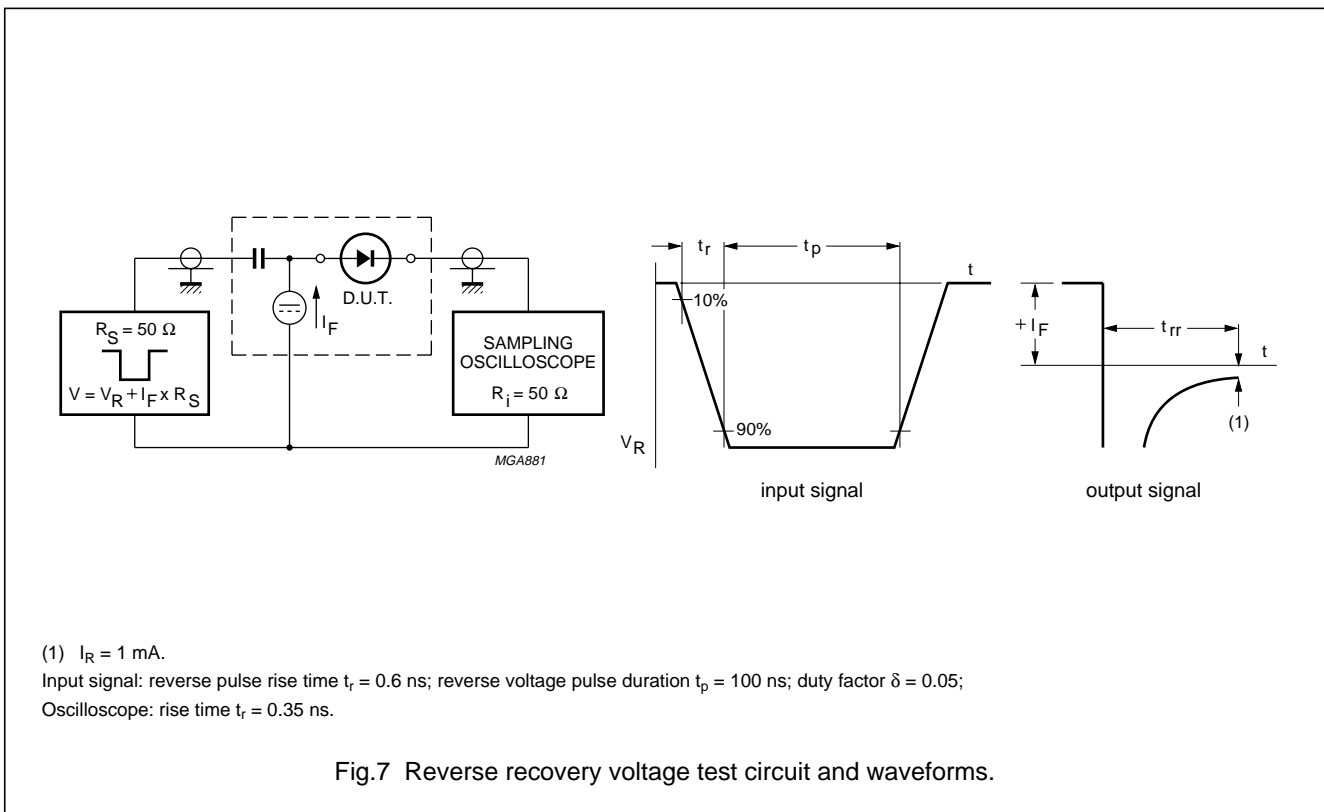
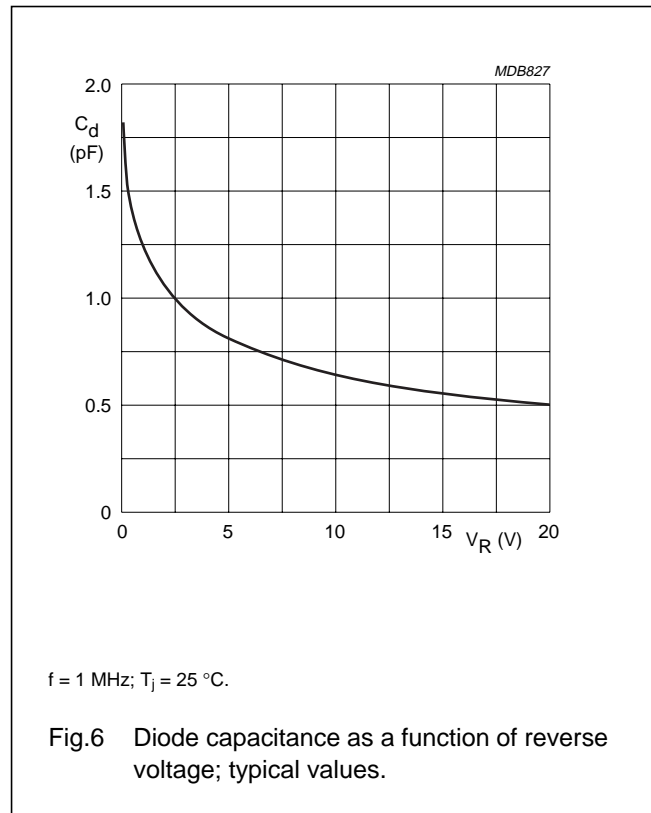
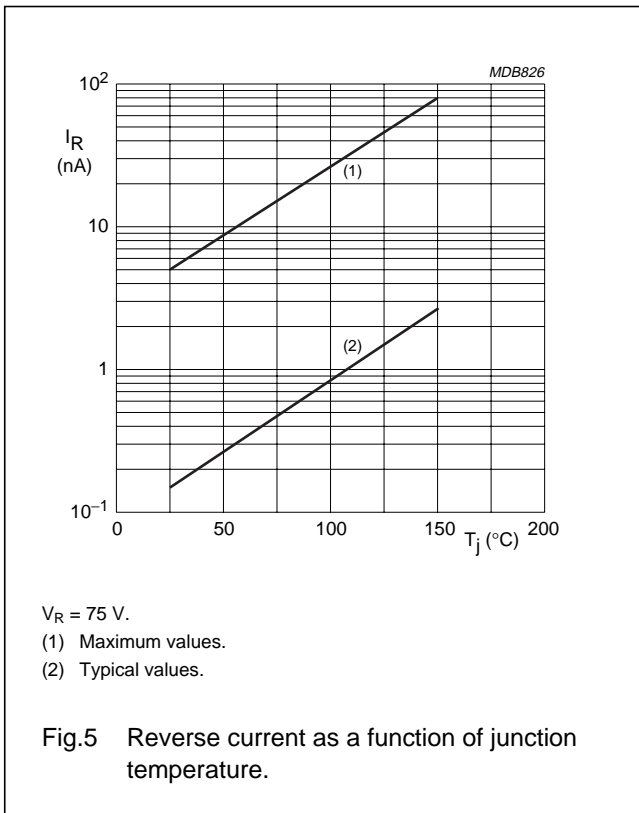
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GRAPHICAL DATA



Low-leakage diode

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Low-leakage diode

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PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523

**DIMENSIONS (mm are the original dimensions)**

UNIT	A	bp	c	D	E	HE	v
mm	0.65 0.58	0.34 0.26	0.17 0.11	1.25 1.15	0.85 0.75	1.65 1.55	0.1

**Note**  
1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			98-11-25- 02-12-13

## Low-leakage diode

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## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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## **Contact information**

For additional information please visit <http://www.semiconductors.philips.com>. Fax: +31 40 27 24825

For sales offices addresses send e-mail to: [sales.addresses@www.semiconductors.philips.com](mailto:sales.addresses@www.semiconductors.philips.com).

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